

AMENDMENTS TO THE SPECIFICATION

Kindly replace paragraph [0018] with the following amended paragraph.

[0018] The apparatus may further include a moving member ~~[[is]]~~ disposed parallel to the latitudinal direction of the frame for moving within a predetermined distance parallel to the longitudinal direction of the frame, wherein the attaching part is coupled to the moving member to cause the attaching part to move together with the moving member.

Kindly replace paragraph [0026] with the following amended paragraph.

[0026] The protection part may be formed ~~[[on]]~~ of aluminum and the frame may be formed of stainless steel.

Kindly replace paragraph [0049] with the following amended paragraph.

[0049] Referring to FIGS. 5, 6A and 6B, the first member 120 is shaped into a bar of a predetermined width w_1 and height h_1 , and has an inner surface 121 facing the inner space 110 and an outer surface 122 (not shown in FIG. 6A) opposite to the inner surface 121. The second member 130 is also shaped into a bar of a predetermined width a and height h_1 , which is identical to the height of the first member 120, and has an inner surface 131 facing the inner space 110 and an outer surface (not shown in FIG. 6A) opposite to the inner surface 131. Both ends of the first member 120 are cut-off with a predetermined depth d from the outer surface 122 to form a notch including a first sectional surface 123 and a second sectional surface 124. Therefore, the notch has depth d that is less than the width w_1 of the first member 120, and a predetermined length l_1 . When the first and second members are coupled with each other, the groove (140 of FIG. 5) is formed along the longitudinal direction

of the frame by the first and second sectional surfaces 123 and 124 of the first member 120 and the inner surface 131 of the second member 130. Although the first and second members may be respectively manufactured and coupled together to form the frame 120, ~~alternately~~ alternatively, the frame may be formed in a body by using a mold for molding the groove, as would be known to one of the ordinary skill in the art.

Kindly replace paragraph [0058] with the following amended paragraph.

[0058] An opening portion 1253 is formed at a center portion of the second face 1252 of the supplementary member 125, and the connecting part 155 installed on the inner surface 151 of the leg portion 154 is removably secured into the opening portion 1253. The connecting part 155 is inserted into the opening portion 1253 and is secured inside the opening portion 1253, so that the moving member 150 is coupled with the first supplementary member 125, and as a result, the moving member 150 is coupled with the frame 100. In addition, a first protruding part 1254 outwardly protrudes from a center portion of the first face 1251. The first protruding part 1254 extends farther out than the outer surface 122 of the first member 120 to be caught on the filter securing part. In an embodiment of the present invention, the first protruding part 1254 is coupled to the first face 1251 such that the first protruding part 1254 can move in and out of the first face 1251. When the frame 100 is not ~~[[need]]~~ needed to catch on the filter securing part, the first protruding part may be fully inserted into the opening portion 1253 and be secured inside the opening portion 1253. As an exemplary embodiment, the first protruding part 1254 is coupled using an elastic securing member in the opening portion 1253. Therefore, the first protruding part 1254 is pushed into the first face 1251 when an external force is applied to the

first protruding part 1254, and the first protruding part 1254 springs up from the first face 1251 by a restitution force of the elastic securing member in the opening portion 1253 to catch the frame on the filter securing part.

Kindly replace paragraph [0075] with the following amended paragraph.

[0075] Meanwhile, recent technology trends for fabricating the semiconductor devices ~~requires~~ require higher purity ~~level~~ levels since the pattern on the wafer becomes more fine and the size of the wafer is significantly increased due to nano-technology, which can process materials on nano-scale views. A 300 mm wafer is transferred into the processing part of the clean room via an equipment front-end module (EFEM). However, the room height of the EFEM is similar to the height of the operator working therein, so that the air filter usually directly contacts the operator. When the maintenance work is performed in the EFEM room, the filter damage caused by the direct contact with the operator as well as the filter damage caused by working instruments has a significant effect on process failure. The filter protection apparatus may be more useful for filtering the air supplied into the EFEM room.